

APPLICATIONS

- ✓ Ethernet - 10/100 Base T
- ✓ FireWire
- ✓ SCSI
- ✓ Bluetooth & RF

IEC COMPATIBILITY (EN61000-4)

- ✓ 61000-4-2 (ESD): Air - 15kV, Contact - 8kV
- ✓ 61000-4-4 (EFT): 40A - 5/50ns
- ✓ 61000-4-5 (Surge): 24A, 8/20 μ s - Level 2(Line-Gnd) & Level 3(Line-Line)

FEATURES

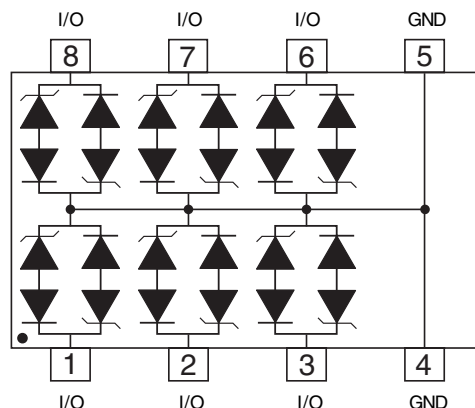
- ✓ 500 Watts Peak Pulse Power per Line (tp=8/20 μ s)
- ✓ Bidirectional Configuration
- ✓ Available in Multiple Voltage Types Ranging From 3.3V to 15V
- ✓ Protects Up to Six (6) Lines
- ✓ ESD Protection > 40 kilovolts
- ✓ Low Capacitance: 8pF
- ✓ RoHS Compliant

MECHANICAL CHARACTERISTICS

- ✓ Molded JEDEC SO-8
- ✓ Weight 70 milligrams (Approximate)
- ✓ Available in Lead-Free Pure-Tin Plating(Annealed)
- ✓ Solder Reflow Temperature:
Pure-Tin - Sn, 100: 260-270°C
- ✓ Consult Factory for Leaded Device Availability
- ✓ Flammability Rating UL 94V-0
- ✓ 12mm Tape and Reel Per EIA Standard 481
- ✓ Marking: Marking Code, Logo, Date Code & Pin One Defined By Dot on Top of Package


SO-8

PIN CONFIGURATION



PLCDA03 thru PLCDA24

DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified

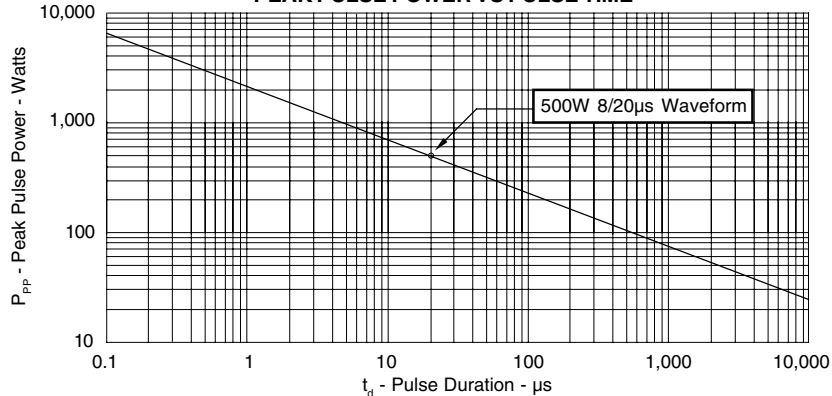
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power ($t_p = 8/20\mu s$) - See Figure 1	P_{PP}	500	Watts
Operating Temperature	T_L	-55 to 150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified

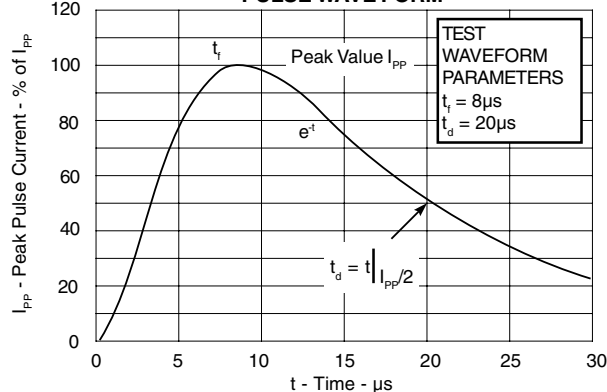
PART NUMBER (See Notes 1)	DEVICE MARKING	RATED STAND-OFF VOLTAGE V_{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA $V_{(BR)}$ VOLTS	MAXIMUM CLAMPING VOLTAGE (See Fig. 2) @ $I_p = 1A$ V_C VOLTS	MAXIMUM CLAMPING VOLTAGE (See Fig. 2) @ 8/20 μs $V_C @ I_{PP}$	MAXIMUM LEAKAGE CURRENT @ V_{WM} I_b μA	MAXIMUM CAPACITANCE (See Note 1) @ 0V, 1 MHz C pF
PLCDA03C-6	PRS	3.3	4.5	7.0	20.0V @ 35.0A	125	8
PLCDA05C-6	PRT	5.0	6.0	9.8	24.0V @ 42.0A	20	8
PLCDA08C-6	PRW	8.0	8.5	13.4	26.0V @ 34.0A	10	8
PLCDA12C-6	PRV	12.0	13.3	19.0	33.0V @ 21.0A	2	8
PLCDA15C-6	PRU	15.0	16.7	22.0	39.0V @ 17.0A	2	8

Note 1: Capacitance between I/O pins and ground (pins 4 & 5) is typically 8pF. Capacitance between I/O pins is typically 4 pF.

**FIGURE 1
PEAK PULSE POWER VS PULSE TIME**

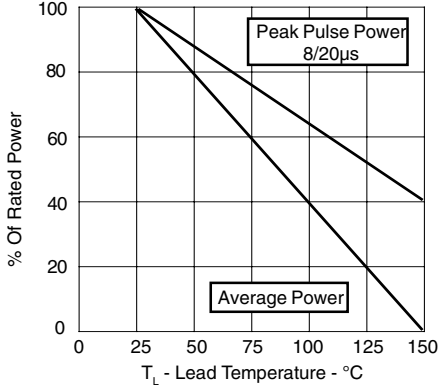


**FIGURE 2
PULSE WAVE FORM**

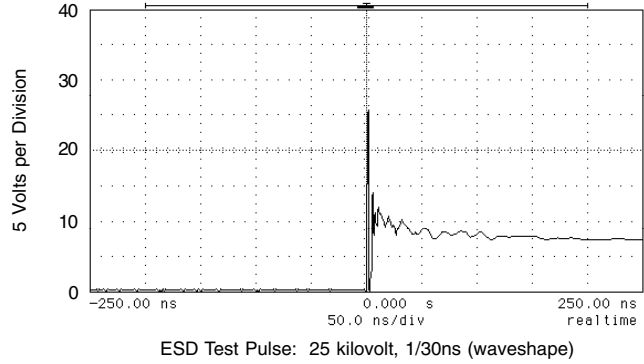


GRAPHS

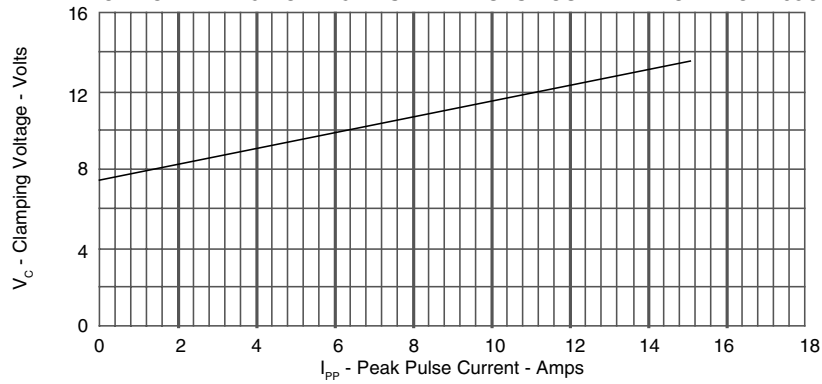
**FIGURE 3
POWER DERATING CURVE**



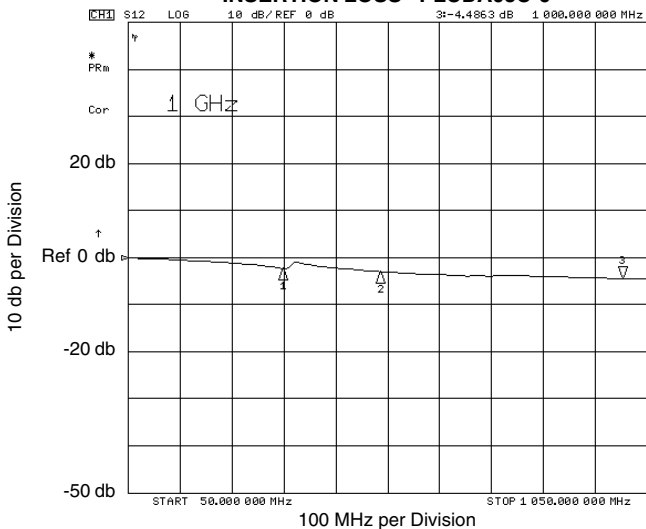
**FIGURE 4
OVERSHOOT & CLAMPING VOLTAGE FOR PLCDA05C-6**



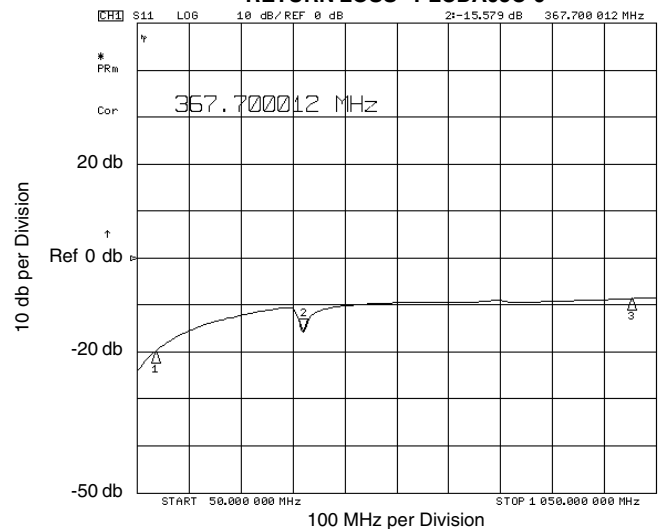
**FIGURE 5
TYPICAL CLAMPING VOLTAGE VS PEAK PULSE CURRENT FOR PLCDA05C-6**



**FIGURE 6
INSERTION LOSS - PLCDA05C-6**



**FIGURE 7
RETURN LOSS - PLCDA05C-6**



PLCDA03 thru PLCDA24

APPLICATION NOTE

The PLCDAxxC-6 Series are low capacitance, bidirectional TVS arrays that are designed to protect I/O or high speed data lines from the damaging effects of ESD or EFT. This product series has a surge capability of 500 Watts P_{PP} per line for an 8/20 μ s waveshape and offers ESD protection > 40kv.

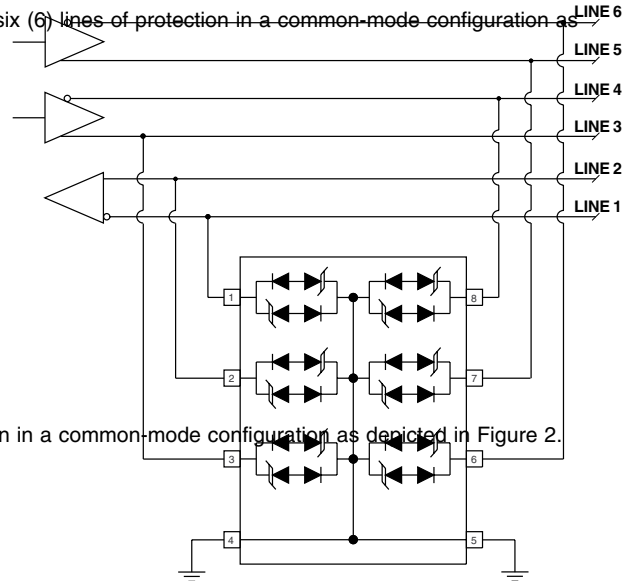
BIDIRECTIONAL COMMON-MODE CONFIGURATION (Figure 1)

Ideal for use multimode transceiver I/O lines, the PLCDAxxC-6 Series provides up to six (6) lines of protection in a common-mode configuration as depicted in Figure 1.

Circuit connectivity is as follows:

- ✓ Line 1 is connected to Pin 1.
- ✓ Line 2 is connected to Pin 2.
- ✓ Line 3 is connected to Pin 3.
- ✓ Line 4 is connected to Pin 8.
- ✓ Line 5 is connected to Pin 7.
- ✓ Line 6 is connected to Pin 6.
- ✓ Pins 4 and 5 are connected to Ground.

Figure 1: Typical Transceiver Protection Circuit



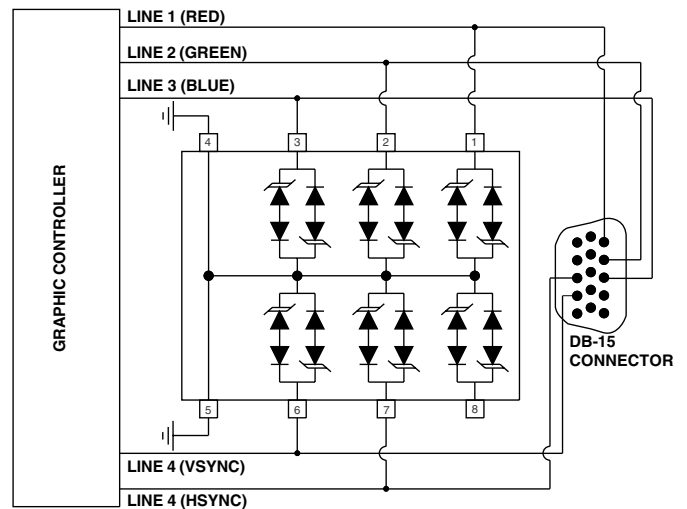
BIDIRECTIONAL COMMON-MODE CONFIGURATION (Figure 2)

The PLCDAxxC-6 Series also provides video line applications six (6) lines of protection in a common-mode configuration as depicted in Figure 2.

Circuit connectivity is as follows:

- ✓ Line 1 (Red) is connected to Pin 1.
- ✓ Line 2 (Green) is connected to Pin 2.
- ✓ Line 3 (Blue) is connected to Pin 3.
- ✓ Line 4 (VSYNC) is connected to Pin 6.
- ✓ Line 5 (HSYNC) is connected to Pin 7.
- ✓ Pins 4 and 5 are connected to Ground.

Figure 2: Typical Video Line Protection Circuit



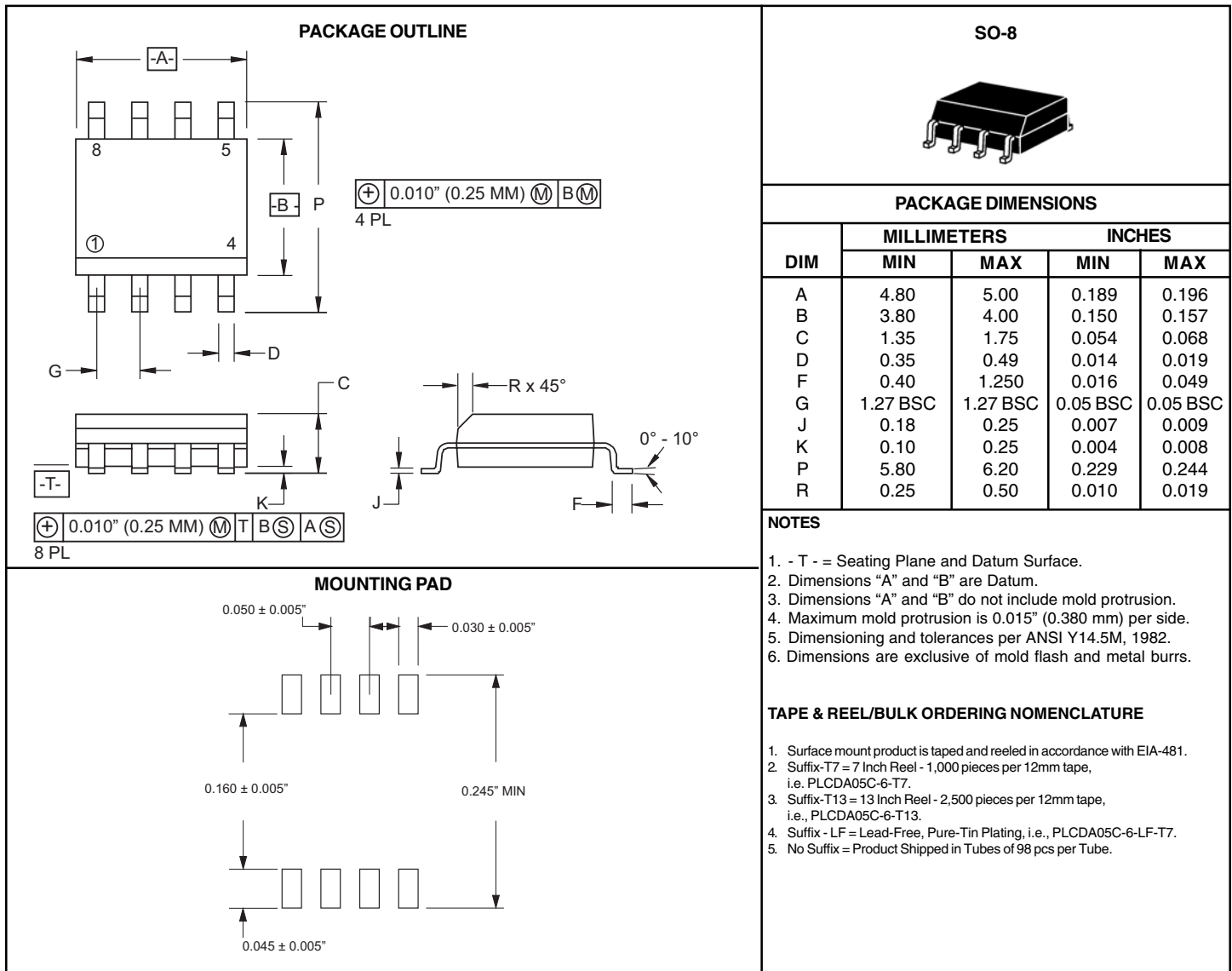
CIRCUIT BOARD LAYOUT RECOMMENDATIONS

Circuit board layout is critical for Electromagnetic Compatibility (EMC) protection. The following guidelines are recommended:

- ✓ The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- ✓ The path length between the TVS device and the protected line should be minimized.
- ✓ All conductive loops including power and ground loops should be minimized.
- ✓ The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- ✓ Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

PLCDA03 thru PLCDA24

SO-8 PACKAGE OUTLINE & DIMENSIONS



COPYRIGHT © ProTek Devices 2007

SPECIFICATIONS: ProTek reserves the right to change the electrical and or mechanical characteristics described herein without notice (except JEDEC).

DESIGN CHANGES: ProTek reserves the right to discontinue product lines without notice, and that the final judgement concerning selection and specifications is the buyer's and that in furnishing engineering and technical assistance, ProTek assumes no responsibility with respect to the selection or specifications of such products.

ProTek Devices
 2929 South Fair Lane, Tempe, AZ 85282
 Tel: 602-431-8101 Fax: 602-431-2288
 E-Mail: sales@protekdevices.com
 Web Site: www.protekdevices.com